L Number	Hits	Search Text	DB	Time stamp
1	66	205/96.ccls. and semiconductor	USPAT;	2004/09/21 14:15
		•	US-PGPUB;	
			EPO; JPO;	
		•	DERWENT	
-	80	204/230.7.ccls.	USPAT;	2003/08/26 18:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	5	204/230.7.ccls. and semiconductor NEAR wafer	USPAT;	2003/08/26 18:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	